

**Amendments to the Claims:**

This listing of Claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

Claim 1(Currently amended):

1. A method for preventing edge peeling defect, comprising:  
forming a thin film on a wafer;  
forming a patterned~~mental~~ metal structure on said wafer;  
planarizing the surface of said wafer to remove redundant ~~patterned~~  
~~mental~~ metal structure, wherein [[a]] ~~an explored~~ exposed part of said thin  
film at an edge of said wafer is ~~explored~~ exposed after planarizing; and  
removing said ~~explored~~ exposed part of said thin film at said edge of said  
wafer.

Claim 2(Currently amended):

The method according to claim 1, wherein said thin film comprises a  
barrier layer for preventing ~~mental~~ metal diffusion.

Claim 3(Original):

The method according to claim 1, wherein the material of said barrier layer  
is chosen from the group comprising the following: Ta, TaN, TiN and TiW.

Claim 4(Original):

The method according to claim 1, wherein said thin film is formed by  
physical vapor deposition.

Claim 5(Currently amended):

The method according to claim 1, wherein said ~~patterned mental~~ metal

structure comprises an interconnect layer.

Claim 6(Currently amended):

The method according to claim 5, wherein said ~~patterned-metal~~ metal structure is chosen from the group comprising the following: copper and aluminum.

Claim 7(Currently amended):

The method according to claim 1, wherein the step for removing said ~~explored~~ exposed part of said thin film comprises etching and chemical mechanical polishing.

Claim 8(Currently amended):

The method according to claim 1, wherein said step for removing said ~~explored~~ exposed part of said thin film ~~explored~~ exposed comprises removing the residual of said ~~patterned-metal~~ metal structure by planarizing.

Claim 9(Currently amended):

The method according to claim 1, wherein said step for removing said ~~explored~~ exposed part of said thin film is at the edge bevel of said wafer.

Claim 10(Currently amended):

The method according to claim 1, wherein said step for removing said ~~explored~~ exposed part of said thin film is at the backside of said wafer.

Claim 11(Currently amended):

The method according to claim 1, wherein said step for removing said ~~explored~~ exposed part of said thin film employs an edge bevel removal technology.

Claim 12(Currently amended):

The method according to claim 11, wherein said step for removing said ~~explored~~ exposed part of said thin film employs an acid solution.

Claim 13(Currently amended):

The method according to claim 11, wherein said step for removing said ~~explored~~ exposed part of said thin film employs an edge polishing technology.

Claim 14(Currently amended):

The method according to claim 13, wherein said step for removing said ~~explored~~ exposed part of said thin film employs a base slurry.

Claim 15(Currently amended):

The method according to claim 13, wherein said step for removing said ~~explored~~ exposed part of said thin film comprises a treatment of wafer drying.

Claim 16(Currently amended):

A method for preventing edge peeling defect, comprising:

forming a barrier layer on a wafer;

forming a metal interconnect layer onto said barrier layer, wherein said barrier layer at said wafer edge is not covered by said metal interconnect layer; and

removing said barrier layer not covered by said metal interconnect layer, annealing said wafer; and

planarizing the metal interconnect layer and removing the redundant metal on the wafer.

Claim 17(Original):

The method according to claim 16, wherein the material of said barrier

layer is Ta.

Claim 18(Original):

The method according to claim 16, wherein the material of said barrier layer is TaN.

Claim 19(Original):

The method according to claim 16, wherein said metal interconnect layer is a copper interconnect layer.

Claim 20(Currently amended):

The method according to claim 16, wherein said metal interconnect comprises said thin film ~~explored~~ exposed at the wafer backside.

Claim 21 (Currently amended):

The method according to claim 16, wherein said step for removing said barrier layer not covered by said metal interconnect layer comprises removing said thin film ~~explored~~ exposed at the wafer backside.

Claim 22(Currently amended):

The method according to claim 16, wherein said step for removing said barrier layer not covered by said metal interconnect layer comprises removing ~~the~~ an incompletely patterned part of said ~~metal~~ metal interconnect layer ~~upper-on~~ on said barrier layer.

Claim 23(Original):

The method according to claim 16, wherein said step for removing said barrier layer not covered by said metal interconnect layer comprises an edge bevel removal treatment.

Claim 24(Original):

The method according to claim 23, wherein said step for removing said barrier layer not covered by said metal interconnect layer employs an acid solution.

Claim 25(Original):

The method according to claim 23, wherein said step for removing said barrier layer not covered by said metal interconnect layer employs an acid solution comprising nitric acid and hydrofluoric acid.

Claim 26(Original):

The method according to claim 9, wherein said step for removing said barrier layer not covered by said metal interconnect layer comprises an edge polishing treatment.

Claim 27(Original):

The method according to claim 13, wherein said step for removing said barrier layer not covered by said metal interconnect layer employs a base slurry.

Claim 28(Original):

The method according to claim 25, wherein the pH of said base slurry is pH 7~12.

Claim 29(Original):

The method according to claim 27, wherein said step for planarizing the metal interconnect layer and removing the redundant metal on the wafer comprises etching for planarizing and chemical mechanical polishing.